

WHAT IS CLAIMED IS:

1. A metal/ceramic circuit board comprising:
a ceramic substrate; and
a metal circuit plate arranged on said ceramic substrate, said metal circuit plate having a thickness which is more than 0.25 mm and which is less than 0.3 mm, and said metal circuit plate having a skirt spreading length of less than 50 μ m, said skirt spreading length being a distance between a plane perpendicular to a principal plane of said metal plate at one end of a bottom face of said metal plate and a plane perpendicular to a principal plane of said metal plate at one end of a top face of said metal plate on the same side as said one end of said bottom face of said metal plate assuming that said distance is positive when said bottom face has a greater area than that of said top face.
2. A metal/ceramic circuit board as set forth in claim 1, wherein said metal circuit plate is bonded directly to said ceramic substrate.
3. A metal/ceramic circuit board as set forth in claim 1, wherein said metal circuit plate is treated by nickel plating, nickel alloy plating, gold plating or preservation.
4. A metal/ceramic circuit board as set forth in claim 1, wherein said metal circuit plate is bonded to said ceramic substrate via a brazing filler metal.
5. A metal/ceramic circuit board as set forth in claim 4, wherein said brazing filler metal is made of a material selected from the group consisting of alloys and compounds containing Ag and an active metal, alloys and compounds containing Al, and mixtures thereof.
6. A metal/ceramic circuit board as set forth in claim 4, wherein said metal circuit plate and said brazing filler metal are treated by nickel plating, nickel alloy plating, gold plating

or preservation.

7. A metal/ceramic circuit board as set forth in claim 1, wherein said ceramic substrate is formed of a material selected from the group consisting of oxides, nitrides and carbides.

8. A metal/ceramic circuit board as set forth in claim 1, wherein said metal circuit plate is formed of a material selected from the group consisting of copper, aluminum, and alloys thereof.

9. A metal/ceramic circuit board as set forth in claim 1, which is a metal/ceramic circuit board on which a super power element is mounted.

10. A metal/ceramic circuit board as set forth in claim 1, which is a metal/ceramic circuit board having a fine pattern on which a Peltier element or a high frequency circuit is mounted.

11. A module assembled by using a metal/ceramic circuit board as set forth in claim 1.